

REMARKS/ARGUMENTS

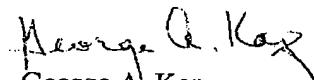
Presently pending are claims 1-8 and 10-25. Claim 9 has been cancelled.

Claims 1-8 and 10-25 were objected as being informal. It is believed that the objection has been satisfied by removing reference to the implant damaged stiffening material. It is also believed that the objection to claims 10-25 is unfounded since these claims are devoid of any reference to the implant damaged stiffening material. Correction is requested.

Claims 1-4 and 7 were rejected under 35 USC 102(b) as being anticipated by the Henley reference; claims 5, 6 and 8 were rejected under 35 USC 103(a) as being unpatentable over the Henley reference in view of the Kub reference; claims 10-19 and 21-25 were rejected under 35 USC 103(a) as being unpatentable over the Henley reference in view of the Lutzen, the Kub, and the Lee references; and claim 20 was rejected under 35 USC 103(a) as being unpatentable over the Henley reference in view of the Lutzen (169), the Kub, the Lee, and the Srickrishan references. These rejections are essentially the same as in the first rejection dated Nov. 22, 2002. It is believed that any anticipation or obviousness rejection based on the Henley reference will not enable a person skilled in the art to practice the method claimed herein. As discussed earlier, the Henley reference is directed to cleaving of a substrate whereas here, the invention is directed to a method for making a thin film device wherein a single crystal semiconducting substrate is bonded to a flexible substrate. Claims 1 and 2 were amended to remove reference to the stiffening layer and to add temperature limitations. It is due to the Examiner's hindsight knowledge of this disclosure that the rejections were concocted.

It is requested that the pending claims herein be allowed and the case be passed to issue,

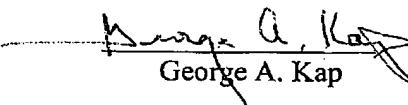
Sincerely,


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CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this paper is being faxed to the PTO on the date shown below.

12-6-05
Date


George A. Kap